

# Epoxy Resin 701AB

## I. Statement of purpose

Epoxy Resin 701AB is an epoxy resin bonding adhesive cured at room temperature and low temperature, easy to operate, fast curing, strong adhesive force, and can be cured at extra temperature. It is specially used for metal bonding, electronic product bonding, hard material bonding and mold filling, as well as insulation of other electronic parts, moisture-proof potting, and confidentiality sealing.

## II. Pre-sclerotic properties.

	A glue 701A	curing agent 701B
Color:	colorless and transparen	colorless and transparen
weight:	1.15	1.05
Viscosity 25℃:	8000-12000CPS	5500-8500CPS

## III. Conditions of use

- 1)mixing ratio: A: B=100: 100 (weight ratio)
- 2)hardening condition: 25℃×5min (2g)
- 3)usable time: 25℃×2min (10g)

## IV. Methods of use

1. Working environment: keep the glue container clean, A, B components strictly according to the weight ratio, accurate weighing, clockwise along the inner wall of the container to mix well and stand for 3-5 minutes after use.
2. Depending on the operating time and dosage of the glue, to avoid waste. When the temperature is lower than 15 ℃, please preheat the A glue to 30 ℃ before glue mixing, easy to operate (low temperature A glue will be thickened); must seal the lid after use, to avoid the product scrapped due to moisture absorption.
3. When the relative humidity is greater than 85%, the surface of the cured material is easy to absorb water in the air, forming a layer of white mist, so when the relative humidity is greater than 85%, it is not suitable for room temperature curing, and it is recommended to use heating curing.

## V. Properties after hardening

1)hardness:	shore D	<u>&lt;85</u>
2)withstand voltage:	KV/mm	22
3)bending strength:	Kg/mm2	24
4)bending strength:	Ohm3	1x10 <sup>15</sup>
5)surface resistance:	Ohmm2	5X10 <sup>15</sup>
6) thermal conductivity:	W/M.K	0.61
7) electrostatic losses:	1KHZ	0.42
8) heat distortion temperature:	℃	140
9) compressive strength:	%	<0.15
10)compressive strength:	Kg/mm2	12.5

The above performance data are typical data measured in a laboratory environment with a temperature of 25℃ and a humidity of 70%, and are for customers' reference only.